

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

PDIP

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TOTAL MASS (g) : 0.501973

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004803 | 1000000 | 9568.23730469 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.001150 | 1000000 | 2290.95825195 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.089088 | 580000 | 177475.578125 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.064512 | 420000 | 128516.796875 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.153600 | 1000000 | 305992.375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.012410 | 1000000 | 24723.0078125 | | |
| | | External Plating Total: | | | | 0.012410 | 1000000 | 24723.0078125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001228 | 1000000 | 2446.34521484 | | |
| Internal Plating Total: | | | | 0.001228 | 1000000 | 2446.34521484 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001276 | 750000 | 2541.96801758 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000425 | 250000 | 846.658569336 | | |
| Die Attach Total: | | | | 0.001701 | 1000000 | 3388.6262207 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.078431 | 240000 | 156245.34375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.003268 | 10000 | 6510.30615234 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.235292 | 720000 | 468734.0625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.009804 | 30000 | 19530.9179688 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.326795 | 1000000 | 651020.625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000286 | 1000000 | 569.751342773 | | |
| | | | | | TOTAL MASS (g) : | 0.501973 | | |